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Rogers Corporation Offers Alternative Copper Option for RO4730G3 Laminates for Cost-Effective High Performance PCB Antennas & Active Antenna Arrays for 5G & IoT

Chandler, AZ - Rogers Corporation **(NYSE:ROG)** now offers RO4730G3™ UL 94 V-0 antenna-grade laminates manufactured with standard profile electrodeposited copper foil to meet present and future performance requirements in active antenna arrays and small cells, notably in Internet of Things (IoT) applications as well as emerging 5G wireless systems. With the option of multiple copper foil offerings, design flexibility increases and rounds out the performance versus cost portfolio.

RO4730G3 ceramic hydrocarbon laminates were originally introduced with a standard profile low-loss LoPro® copper foil option. While LoPro copper foil provides excellent passive-intermodulation (PIM) performance (typically better than -160 dBc) and has gained popularity for intermodulation (IM) sensitive, high-frequency antennas, as 5G designs evolve, PIM has become less important on some

applications. RO4730G3 laminates with standard profile electrodeposited copper provide an optimum blend of price, performance, and durability.

RO4730G3 laminates provide the low dielectric constant (Dk) of 3.0 favored by antenna designers, held to a tolerance of ±0.05 through the thickness (z axis) when measured at 10 GHz. These laminates are 30% lighter than PTFE circuit materials and feature a high glass transition temperature (T_g) of better than +280°C for compatibility with automated assembly techniques. RO4730G3 circuit laminates exhibit low z-axis coefficient of thermal expansion (CTE) of 30.3 ppm/°C from -55 to +288°C for reliable plated through holes (PTHs) in multilayer circuit assemblies and are lead-free-process compatible.

About Rogers Corporation

Rogers Corporation (NYSE:ROG) is a global leader in engineered materials to power, protect and connect our world. With more than 180 years of materials science experience, Rogers delivers high-performance solutions that enable advanced connectivity and advanced mobility applications, as well as other technologies where reliability is critical. Rogers delivers Power Electronics Solutions for energy-efficient motor drives, vehicle electrification and alternative energy; Elastomeric Material Solutions for sealing, vibration management and impact protection in mobile devices, transportation interiors, industrial equipment and performance apparel; and Advanced Connectivity Solutions for wireless infrastructure, automotive safety and radar systems. Headquartered in Arizona (USA), Rogers operates manufacturing facilities in the United States, China, Germany, Belgium, Hungary and South Korea, with joint ventures and sales offices worldwide. For more information, visit www.rogerscorp.com.